

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC25BS8xxxMR-G

Typical Mass: 17 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.627	Silicon	36900	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	5.952	Copper	350100	7440-50-8
	0.024	Tin	1400	7440-31-5
	0.023	Zinc	1300	7440-66-6
	0.026	Chromium	1500	7440-47-3
	0.351	Silver	20700	7440-22-4
	Die attach	0.049	Silver	2900
	0.009	Epoxy	500	—
Bonding wire	0.045	Gold	2700	7440-57-5
Resin	8.030	Silica	472300	60676-86-0
	0.668	Epoxy resin	39300	—
	0.534	Phenol resin	31400	—
	0.262	Metal hydroxide	15400	—
Plating	0.400	Tin	23500	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."